tet No.: 085027-0104

**PATENT** 

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Customer Number: 89518

Mou-Shiung Lin, et al.

Confirmation Number: 8665

Application No.: 10/755,042

Group Art Unit: 2815

Filed: January 09, 2004

For:

INTEGRATED CHIP PACKAGE STRUCTURE USING SILICON SUBSTRATE AND

METHOD OF MANUFACTURING THE SAME

## TRANSMITTAL OF POWER OF ATTORNEY

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Transmitted herewith is a Power Of Attorney to Prosecute Applications Before the USPTO, together with a Statement Under 37 CFR 3.73(b), which revokes all previous powers of attorney given in the above-identified application and associates the application with Customer Number 89518.

Respectfully submitted,

McDERMOTT WILL & EMERY LLP

Dennis A. Duchene Registration No. 40,595

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Phone: 858.720.3300 DAD:MWE

Facsimile: 858.720.7800 Date: October 7, 2009 Please recognize our Customer No. 89518 as our correspondence address.